Compliant with IEC 62474/ D9.00

Basic Substance	MICROCHIP Semiconductor Device Type: SZ-C0 144 WFBGA 9x9x0.8mm SAC (SZX)				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
Section Compared			"Contained In"				64.62	(mg) Total	Mold Compound	% ot Total Weigh	t 50.37
Strock Properties Propert			•	_			002		•	·	
Sport Residual 1900											
Peter Rest \$600.394 Mode Compound 15th 15											-
Apartment and its compounds (Apartment and its compounds) (A											
Copper	Aluminium and its compounds	Trade Secret	Mold Compound	1.516	1.945	15,161	A	luminium and its compounds	Trade Secret	3.01	
Class Interest	Carbon Black	1333-86-4	Mold Compound	0.277	0.355	2,770		Carbon Black	1333-86-4	0.55	
Pients (Aprilled by Populard 1903 95-5 Leef Frame 9,063 11,028 90,030 1,028 1,									Total	100.00	
Siles, chemosity progress 7561-9-9 Leaf Frame 3.889 4.347 3.3891 1.484 7.484526 1.484 1.							54.34				t 42.35
Nice											
Basis 7727-43-7											_
Magnetic N 250 1,000 1											
Analise (V 250 2006-386 Load Frame 0.35 0.457 1.087 0.470											_
Administrative/protections/p											1
Adminish physioside-coids 24625776 Load Frame 0,212 0,272 2,118 (Minish Archive Copyrights Copyri											1
Aluminium phytroxide coxide											1
Monthal/Actific Copylmen Trads Secret	Aluminium-hydroxide-oxide	24623-77-6		0.212	0.272	2,118	(2-M			0.80	1
Phono Resin Trade Socret De Attach 0.003 0.004 28 0.02 0.005 0.004 0.005 0		7440-57-5					,	Misc.		1.50	
Prince P											
Signature Trade Secret Die Allasch 0.001 8 0.03 (mg) Tetal Die Allasch 5.67 Teal Weight 0.02								Gold			
Silton 7440-21-3 Chip (De) 0.130 0.167 1.300 Copper 7440-50-8 Wire Bond Copper palladum costed (CuPd) 0.422 5 Palladum 7440-05-3 Wire Bond Copper palladum costed (CuPd) 0.008 0.010 0.75 Silver 7440-22-4 Palladum 1940-22-4 Palladum 1940-22-4 Palladum 1940-23-5 Palladum 1940-23-6											
Copper 7440-5518 Wire Board Copper palladium coated (CuPd) 0.422 0.542 4.225 Pallatium 7440-563 Wire Board Copper palladium coated (CuPd) 0.008 0.010 75 Fin 7440-575 Pallating on external leads (pins) (SAC105) 0.007 0.086 570 Copper 7440-575 Pallating on external leads (pins) (SAC105) 0.007 0.086 570 Total 0.1283 Total 0.000 0.008 0.001 0.008 0.000 0.008 0.000 Total 0.000 0.008 0.000 0.008 0.000 0.008 0.000 0.008 0.000 0.008 0.000 Total 0.000 0.008 0.000							0.03				t 0.02
Falladium 7440-05-3 Wire Bond Copper palladium coated (CuPd) 0.008 0.010 75 Silver 7440-22-4 Plating on external leads (pins) (SAC105) 6.00 8.467 65.995 Copper 7440-22-4 Plating on external leads (pins) (SAC105) 0.067 0.068 670 O.1283 g Total Mass TOTALS: 100.000 128.300 1,000.000 O.1283 g Total Mass Total 100.000 128.300 1,000.000 O.1283											
Tin 7440-31-5 Plating on external leads (pins) (SAC105) 6.800 8.467 65.995 Total 740-2-4 Plating on external leads (pins) (SAC105) 0.057 0.086 670 Total 100.00 128.30 0.043 3.35 0.17 (mg) Total Chip (Dis) % of Total Weight 0.13 100.00 128.30 0.043 0.043 3.35 0.17 (mg) Total Chip (Dis) % of Total Weight 0.13 100.00 128.30 0.043 0.043 0.043 0.043 0.043 0.043 0.043 0.043 0.045 0											
Silver 7440 524 Pilling on external leads (pins) (SAC 105) 0.087 0.086 670 Copper 7440 528 Pilling on external leads (pins) (SAC 105) 0.034 0.033 0.04 0.043 335 0.17 (mg) Total Chip (Dis) vol 740 140 (Dis) vol 740 (Dis) vol											-
Copper 7440-59-8 Plating on external leads (pins) (SAC105) 0.034 0.043 335 0.07 (mg) Total Chip (Dis) % of Total Weight 0.13 0.000 0.028 0.000								SIO2 FIIIEI			_
O.1283 g Total Mass S semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March 5) and 2002/53/EC (End-0f-Life Vehicles (ELV) without exemption (zero) Mirror Band Copper paliadium Cocined (CuPd) Copper T440-50-8 88.25 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 Copper T440-50-8 88.25 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 Copper T440-50-8 88.25 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 Copper T440-50-8 88.25 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 Copper T440-50-8 8.80 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 8.00 Copper T440-50-8 8.80 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 8.00 Copper T440-50-8 8.80 (mg) Total Red CuPd) Copper T440-50-8 8.80 (mg) Total Paliadium T440-05-3 1.75 Total 100.00 8.00 Copper T440-50-8 8.80 (mg) Tot							0.17	(mg) Total			
O.1283 g Total Mass semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March (5) and 2002/55/EC (End-of-Life Vehicles (ELV) without exemption (zero) mpliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology orporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if v, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Iding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at 200.000 members of the chemical substance, if v is not believe the threshold of regulatory concern for any regulatory scheme world-wide. Iding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at 200.000 members of the chemical substance, if v is protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and it reports to the post of its knowledge and belief, as of the date listed in this form because it has been compiled based on the ranges provided in Makerial Suppliers. Supplier transition is often protected from disclosure as trade secrets and some information in why not have been provided by a warrant exemple to the special provided by Microchip Technology incorporated some provided on warranty, express or implied, with respect to the information in Microchip's standard terms and conditions of sale. Th	Сорры	7440 00 0					0.17				0.13
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chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology orporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if , is not below the threshold of regulatory oscheme world-wide. Iding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at policy in the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and tain "reels" may be made from PVC plastic. Tochip Technology incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology incorporated cannot guarantee the inpleteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers, form disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers, and non-metal information is vided only as estimates of the average weight of these parts and the average weight of an access the substance in the finished parts. To tail 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (mg) Total Plating on external leads (pins) (SAC105) % of Total Weight 6.7 Total 100.00 8.60 (m	mpliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.							Copper		98,25	
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a protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and tain "reels" may be made from PVC plastic. Roccompliance Post Post			stics. You can access the UL iQTM family of databases	to obtain a tes	t report at				Total	100.00	
ir ortiginal packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the mpleteness and accuracy of data in this form because it has been compiled based on the ranges provided by subcontract assemblers and raw material suppliers. Suppliers of the protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. Total 100.00 The A40-31-5 98.50 Tin 7440-31-5 98.50 Tin 7440-31-5 98.50 Tin 7440-31-5 98.50 Total 100.00 Tota							8.60	(mg) Total		% of Total Weigh	t 6.7
ranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's tations, sales order acknowledgement, and invoices. rochip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or erwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or in Scrifficate of Compliance for semiconductor products. embled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at	eir original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the mpleteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier ormation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is by ided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.							Tin	7440-31-5	98.50	
terwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or this Certificate of Compliance for semiconductor products. Sembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at								Silver	7440-22-4	1.00	
								Copper	7440-50-8	0.50	
v://echa.europa.eu/web/guest/candidate-list-table	sembled package referenced above is EU REACH compliant based	on the latest SVH	C candidate list of ECHA which can be found at					-	Total	100.00)
	://echa.europa.eu/web/guest/candidate-list-table										

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